TOSHIBA Power Transistor Module Silicon NPN&PNP Epitaxial Type (Darlington power transistor 6 in 1)

MP6301

High Power Switching Applications

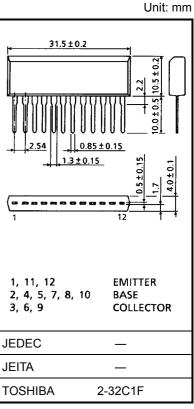
3-Phase Motor Drive and Bipolar Drive of Pulse Motor

- Small package by full molding (SIP 12 pin)
- High collector power dissipation (6 devices operation) : $P_T = 4.4 \text{ W} (T_a = 25^{\circ}\text{C})$
- High collector current: $I_{C}(DC) = \pm 3 A (max)$
- High DC current gain: $h_{FE} = 2000 \text{ (min)} (V_{CE} = \pm 2 \text{ V}, I_C = \pm 1 \text{ A})$

Maximum Ratings (Ta = 25°C)

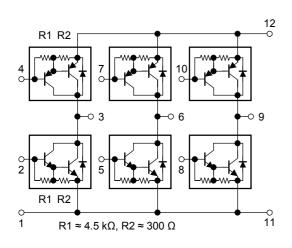
Characteristics		Symbol	Ra	Unit	
		Gymbol	NPN	PNP	Onic
Collector-base voltage	Collector-base voltage		100	-100	V
Collector-emitter voltage	;	V _{CEO}	80	-80	V
Emitter-base voltage	Emitter-base voltage		8	-8	V
Collector current	DC	Ι _C	3	-3	А
	Pulse	I _{CP}	5	-5	~
Continuous base current		Ι _Β	0.5	-0.5	А
Collector power dissipation		Pc	2.0		W
(1 device operation)		ГC	2	vv	
Collector power dissipation		Рт	4	W	
(6 devices operation)		Г	4	vv	
Junction temperature		Тј	150		°C
Storage temperature range		T _{stg}	-55 to 150		°C

Industrial Applications



Weight: 3.9 g (typ.)

Array Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance of junction to ambient (6 devices operation, Ta = 25°C)	ΣR _{th (j-a)}	28.4	°C/W	
Maximum lead temperature for soldering purposes (3.2 mm from case for 10 s)	TL	260	°C	

Electrical Characteristics (Ta = 25°C) (NPN transistor)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I _{CBO}	V _{CB} = 100 V, I _E = 0 A	_	—	20	μA
Collector cut-off cu	rrent	I _{CEO}	V _{CE} = 80 V, I _B = 0 A	_	—	20	μA
Emitter cut-off curr	ent	I _{EBO}	V _{EB} = 8 V, I _C = 0 A	0.8	_	4.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = 1 mA, I _E = 0 A	100	_	_	V
Collector-emitter b	reakdown voltage	V (BR) CEO	I _C = 10 mA, I _B = 0 A	80	_	_	V
DC ourrent gain		h _{FE (1)}	V _{CE} = 2 V, I _C = 1 A	2000	_	_	
DC current gain		h _{FE (2)}	V _{CE} = 2 V, I _C = 2 A	1000	_	_	
Saturation voltage	Collector-emitter	V _{CE (sat)}	I _C = 2 A, I _B = 4 mA	_	_	1.8	v
	Base-emitter	V _{BE (sat)}	I _C = 2 mA, I _B = 4 mA	_	—	2.3	
Transition frequency		f _T	V _{CE} = 2 V, I _C = 0.5 A	_	100	_	MHz
Collector output capacitance		C _{ob}	V _{CB} = 10 V, I _E = 0 A, f = 1 MHz	_	20	_	pF
	Turn-on time	t _{on}	Input IB1	_	0.4	_	
	Storage time	t _{stg}	$20 \ \mu s$ $B2$ M	_	3.0	_	μs
	Fall time	t _f	I _{B1} = −I _{B2} = 4 mA, duty cycle ≤ 1%	_	0.6	_	

Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I _{FM}	—	—	_	3	А
Surge current	I _{FSM}	t = 1 s, 1 shot	_	_	5	А
Forward voltage	VF	I _F = 1 A, I _B = 0 A	_	_	2.0	V
Reverse recovery time	t _{rr}	- I _F = 3 A, V _{BE} = −3 V, dI _F /dt = −50 A/μs	_	1	_	μs
Reverse recovery charge	Q _{rr}			5	—	μC

Electrical Characteristics (Ta = 25°C) (PNP transistor)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I _{CBO}	V _{CB} = -100 V, I _E = 0 A	—	—	-20	μA
Collector cut-off cu	rrent	I _{CEO}	V _{CE} = -80 V, I _B = 0 A	_	_	-20	μA
Emitter cut-off curr	ent	I _{EBO}	V _{EB} = -8 V, I _C = 0 A	-0.8	_	-4.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = -1 mA, I _E = 0 A	-100	_	_	V
Collector-emitter b	reakdown voltage	V (BR) CEO	I _C = -10 mA, I _B = 0 A	-80	—	_	V
DC ourrent goin		h _{FE (1)}	$V_{CE} = -2 V, I_C = -1 A$	2000	_	_	
DC current gain	h _{FE (2)}	$V_{CE} = -2 V, I_C = -2 A$	1000	_	_	—	
Coturation voltage	Collector-emitter	V _{CE (sat)}	I _C = -2 A, I _B = -4 mA	_	_	-1.8	v
Saturation voltage	Base-emitter	V _{BE (sat)}	$I_{\rm C} = -2$ A, $I_{\rm B} = -4$ mA	_	_	-2.3	
Transition frequency		fT	$V_{CE} = -2 V, I_C = -0.5 A$	_	50	_	MHz
Collector output capacitance		C _{ob}	V _{CB} = -10 V, I _E = 0 A, f = 1 MHz	_	30	_	pF
	Turn-on time	t _{on}	Input IB2 Input →	_	0.4	_	
	Storage time	t _{stg}		_	1.8	_	μs
	Fall time	t _f	20 µs −I _{B1} = I _{B2} = 4 mA, duty cycle ≤ 1%	_	0.4	_	

Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I _{FM}	—	_	_	3	А
Surge current	I _{FSM}	t = 1 s, 1 shot	_	_	5	А
Forward voltage	V _F	I _F = 1 A, I _B = 0 A	_	_	2.0	V
Reverse recovery time	t _{rr}	Ι _F = 3 A, V _{BE} = 3 V, dI _F /dt = −50 A/μs	_	500	_	μs
Reverse recovery charge	Q _{rr}		_	2.7	—	μC

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